



International Conference on Wireless Systems: Computation, Assembling, and Compatibility

— CAC2008

<http://www.compute-online.com>

4-7 Sept'08, Yinhe Dynasty Hotel, Chengdu and Jiuzhaigou, China

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Linking Academy and Industry together in the Wireless World

Second Call For Papers

The International Conference on Wireless Systems: Computation, Assembling, and Compatibility — CAC2008 will be held on 4-7 September 2008 in both Yinhe Dynasty Hotel, Chengdu and Jiuzhaigou Valley, China. The conference is intended to provide an international forum for the exchange of information on the state-of-the-art research and developments in areas of wireless technologies in terms of Computation/Design, Assembling/Fabrication, and Integration/Compatibility issues interesting to both academics and industries. For the detailed conference information, visit the CAC2008 official website at www.compute-online.com.

Technical Areas: The topics of interest are encouraged, but not limited to, the followings:

1. EDA/CAD/CAE/CAM
2. Numerical Methodologies and Algorithms
3. Online/Mobile Computations
4. Device Analysis and Modeling
5. Signal Processing and Coding
6. Antennas/Smart Arrays
7. RFIC/MMIC/MEMS
8. SoC and Verifications
9. RF/Microwave T/R Modules
10. Digital Broadcasting Satellite
11. High-Frequency and High-Speed PCBs
12. Packaging Analysis and Designs
13. Broadband Wireless Technologies
14. Mobile Communications Technologies
15. RFID and Applications
16. Remote and Transportation Applications
17. Embedded Software and Applications
18. EMC/EMI/ESD
19. EM Radiations/Propagations
20. Measurement Techniques
21. Biological and Medical Applications

- Conference proceeding indexed into *IEEE Xplore, & EI*
- Special Journal Issue of *COMPEL* into *Compindex Plus, & EI*

Important Deadline:

Paper Submission
4 July 2008

Registration Open
1 June 2008

Final Acceptance Notification
25 July 2008

Camera Ready
15 Aug 2008



Electronic Paper Submissions: Prospective authors are invited to submit their full technical papers in English but limited to four A4 pages, and be compliant to the standard IEEE Xplore format. The paper should emphasize their original contributions and key findings, and support by important figures, diagrams and simulated/measured results. Each author is limited to 3 papers only. Submission of a paper implies that, for the accepted paper, at least one of the authors will have a full registration for the conference. The authors should submit papers **ONLY** in electronic copies and the manuscript template can be downloaded at www.compute-online.com. Hard copies will not be accepted. All authors can select either oral presentation or poster for the conference. All the qualified papers in the Conference Proceeding will be included in the *IEEE Xplore* database. Selected CAC2008 papers will be published in a special issue of *COMPEL* (Vol.29, No.2, 2010) as journal articles. The International Journal for Computation and Mathematics in Electrical and Electronic Engineering (COMPEL) is indexed and abstracted in both the *Compendex Plus*, and *Engineering Index* databases.

Industry Talk: The conference encourages industry partners to talk about their design IPs and fabs kits, new system design and analysis tools, available semiconductor technologies, assemblies, techniques and processing, manufacturing automations, new industry standards and certificate, and others. These papers will not be inserted in the IEEE Xplore database but will be reviewed accordingly.

Guest Program: For the last day of the conference, an optional visit to Jiuzhaigou Valley, which is a world-renowned visitor destination with most wonderful natural sceneries, lovely animal pandas, and local cultures, will be conducted. You and your family may like to enjoy all these arranged guest program activities. For more information, please visit www.jiuzhai.com.

Workshops/Exhibitions: Workshops/Exhibitions are solicited for the above Technical/Industrial Areas. Interested parties should complete the registrations in advance. The 4-hour Workshops will commence on 4 September 2008. The exhibitions will last in the whole conference period. For further information and registration, kindly contact the conference secretariat at cac2008@compute-online.com.

CAC2008 Sponsorship: The CAC2008 is calling for interested parties for reception sponsorship, website sponsorship, and proceeding advertisement sponsorship. The reception sponsorship package is to offer opportunities for the sponsors to place their Company name and/or logo near the reception room entrance. The website sponsorship package is to offer opportunities for companies to showcase their logo on the CAC 2008 website (www.compute-online.com). Under the proceeding advertisement sponsorship, your Company name and/or logo will appear in the backside cover of the CAC2008 Proceeding.

Best Paper Awards: Two prizes, namely, a best student paper and a young scientist paper, will be awarded in the conference.

